

FAB NOTES :

1. BOARD DIMENSION : 125.73MM X 80.25MM.
2. VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED, PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED VIA TENTING/COVERING REQUIREMENTS.
3. ALL VIAS ARE TENTED ON BOTH SIDES UNLESS OTHERWISE SOLDER MASK IS OPENED IN GERBER.
4. TRACES WITH 6.5MIL TO BE 50 OHMS +/-10% SINGLE ENDED ON TOP LAYER, SIGNAL1, SIGNAL2 & BOTTOM LAYER (L1,L3,L6 & L8).
5. 8.02MIL VIAS NEED TO BE FILLED WITH NON-CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001 ON TOP SIDE ONLY AND +0.000/-0.003 ON BOTTOM SIDE. MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.
6. 8.01MIL VIAS NEED TO BE FILLED WITH NON-CONDUCTIVE EPOXY-RESIN AND OVERPLATE WITH COPPER. SURFACE MUST BE FLAT, FLATNESS TOLERANCE IS +0.000/-0.001 ON BOTTOM SIDE ONLY AND +0.000/-0.003 ON TOP SIDE. MINIMUM ANNULAR RING REQUIREMENT IS WAIVED FOR FILLED VIAS.

LAYER STACK-UP :

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.80mil	3.5	
1	Top Layer		2.80mil		
	Dielectric 1	FR-4 High Tg	4.00mil	4.1	
2	GND1	CF-004	1.40mil		
	Dielectric 2	FR-4 High Tg	8.00mil	4.1	
3	SIGNAL1	CF-004	1.40mil		
	Dielectric 3	FR-4 High Tg	8.00mil	4.1	
4	POWER1	CF-004	1.40mil		
	Dielectric 4	FR-4 High Tg	6.40mil	4.8	
5	POWER2	CF-004	1.40mil		
	Dielectric 5	FR-4 High Tg	8.00mil	4.1	
6	SIGNAL2	CF-004	1.40mil		
	Dielectric 6	FR-4 High Tg	8.00mil	4.1	
7	GND2	CF-004	1.40mil		
	Dielectric 7	FR-4 High Tg	4.00mil	4.1	
8	Bottom Layer		2.80mil		
	Bottom Solder	Solder Resist	0.80mil	3.5	
	Bottom Overlay				

- NOTE : THIS IS AN IMPEDANCE CONTROLLED BOARD.
1. ALL CORE AND PREPREG THICKNESSES ARE UP TO FAB SHOP TO SELECT.
2. EXTERNAL LAYER CU THICKNESSES ARE FINISHED THICKNESS AFTER PLATING.

DRILL TABLE:

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Length	Routed Path Length	Hole Tolerance (Mils)
A	43	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+0.00/-7.874
C	126	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+0.00/-8.00
D	63	8.01mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+0.00/-8.01
B	22	8.02mil (0.204mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+0.00/-8.02
E	593	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+0.00/-10.00
Q	6	12.99mil (0.330mm)	PTH	Round	Top Layer - Bottom Layer	-	-	
F	12	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+/-3.00
G	4	29.92mil (0.760mm)	NPTH	Round	Top Layer - Bottom Layer	-	-	+/-2.00
V	2	29.92mil (0.760mm)	PTH	Rectangle	Top Layer - Bottom Layer	120.08mil (3.050mm)	120.08mil (3.050mm)	
H	15	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+/-3.00
I	12	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+/-3.00
O	1	40.16mil (1.020mm)	PTH	Rectangle	Top Layer - Bottom Layer	140.16mil (3.560mm)	140.16mil (3.560mm)	
S	10	44.88mil (1.140mm)	PTH	Round	Top Layer - Bottom Layer	-	-	
K	4	70.87mil (1.800mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+/-3.00
M	4	92.52mil (2.350mm)	NPTH	Round	Top Layer - Bottom Layer	-	-	+/-2.00
R	1	94.49mil (2.400mm)	NPTH	Round	Top Layer - Bottom Layer	-	-	+/-2.00
N	1	94.49mil (2.400mm)	NPTH	Slot	Top Layer - Bottom Layer	116.14mil (2.950mm)	21.65mil (0.550mm)	+/-2.00
P	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	-	-	+/-3.00
	923 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length - Tool Size - Slot length as defined in the PCB layout

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DESIGN INFORMATION	
MIN. TRACK WIDTH:	5 MIL
MIN. CLEARANCE:	5 MIL
MIN. VIA PAD SIZE:	19,685 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL	

MATERIAL:	
<input type="checkbox"/> FR-408	<input checked="" type="checkbox"/> FR-4 High Tg
<input type="checkbox"/> OTHER	
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10%
<input type="checkbox"/> OTHER	
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
<input type="checkbox"/> OTHER +/-	
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2
<input type="checkbox"/> OTHER +/-	

DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN
<input checked="" type="checkbox"/> NC_DRILL FILES	
PTH COPPER THICKNESS:	<input checked="" type="checkbox"/> 20-30 um
<input type="checkbox"/> OTHER	

BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP
<input checked="" type="checkbox"/> BOTTOM	
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE
<input type="checkbox"/> OTHER	
SOLDER RESIST COLOR:	<input checked="" type="checkbox"/> GREEN
<input type="checkbox"/> OTHER	
<input type="checkbox"/> MATTE	<input checked="" type="checkbox"/> SEMI-GLOSS

SURFACE FINISH:	
<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG)	<input type="checkbox"/> ENEPIG
<input type="checkbox"/> IMM. TIN/SILVER OR EQUIV	<input type="checkbox"/> OTHER

ARRAY/PANEL:	
<input type="checkbox"/> CUT AND TRIM PER M1 BOARD OUTLINE	
<input type="checkbox"/> N.C. ROUTE	<input checked="" type="checkbox"/> V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS ->	<input type="checkbox"/> 1
<input checked="" type="checkbox"/> 2	<input type="checkbox"/> 3
<input checked="" type="checkbox"/> RoHS	<input type="checkbox"/> OTHER PER ORDER

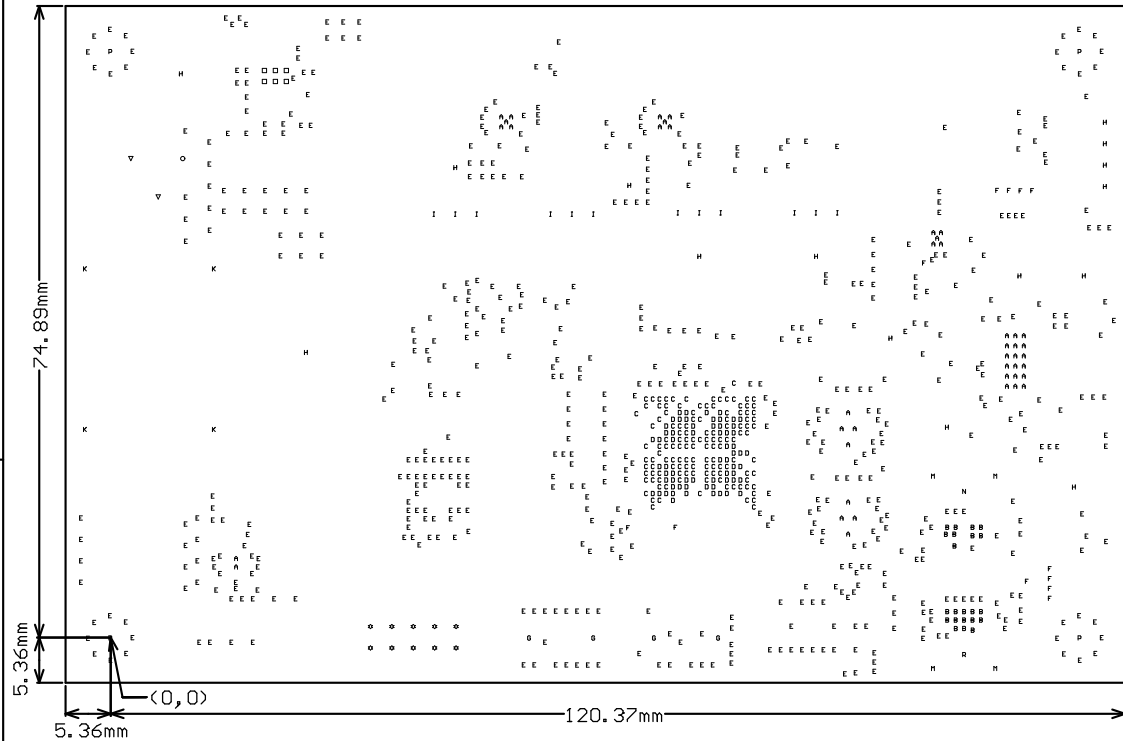
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:	
MICROSECTION: <input type="checkbox"/> YES	
BARE BOARD ELEC. TEST: <input type="checkbox"/> NONE	
<input checked="" type="checkbox"/> REQUIRED	<input type="checkbox"/> PER ORDER
<input type="checkbox"/> XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE	
<input type="checkbox"/> XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE	
<input type="checkbox"/> OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE	
<input type="checkbox"/> LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE	
TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE	



PROJECT TITLE:	
DLP0201AM263Q1EVM	
DESIGNED FOR:	
Public Release	
FILE NAME:	
DLP096B.PcbDoc	

ENGINEER:	LAYOUT BY:
A. Whitehead	A. Whitehead
SCALE: 1.12	ALTUM DESIGNER VERSION:
	23.1.1.15



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: DLP096	REV: B	SUN REV: Not in version control
LAYER NAME = FAB	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 5/1/2024 4:55:42 PM	TEXAS INSTRUMENTS	